



RETRONIX
CONSISTENCY | INNOVATION | QUALITY | PRECISION

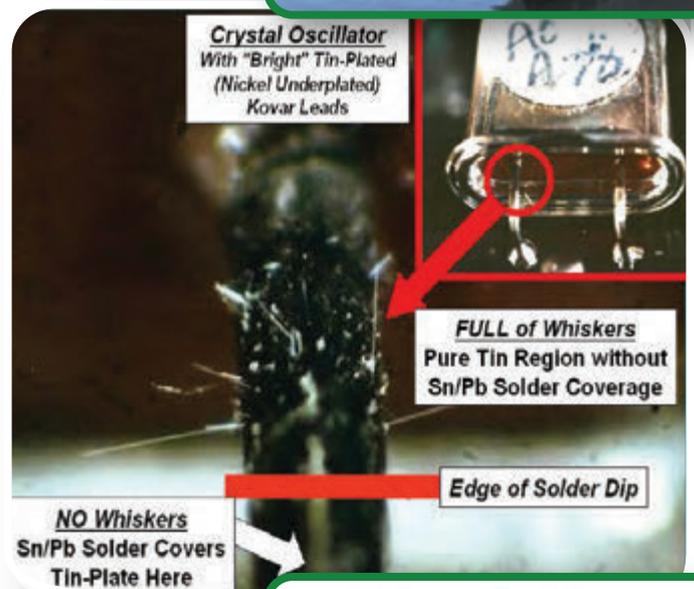
Retronix can help electronic component distributors/brokers win business in the Hi Reliability PCBA industry

Hi Reliability Industries (Aerospace, Defence, Oil & Gas etc) are exempt from using lead free processes. The existence of tin whisker issues means they will not readily move to lead free processes for the foreseeable future. This gives these companies a problem, as most components are only produced now in lead free form, so these companies have to have them converted to tin/lead alloy before assembling them.

This is giving OEMs & CEMS an administrative problem, as each component has to be brought in, in lead free format, then sent to a company like Retronix to be converted to tin/lead, and brought in under a different part number, which adds greatly to the admin & can affect the leadtime.

However Retronix can work with component suppliers to do the conversion for them, enabling the supplier to sell tin/lead components to this sector, making their life much easier.

Whole BOMs can be supplied of tin/lead components, allowing the supplier to gain market share in this high margin business.



Speak to Retronix about how we can help you increase your market share

FOR MORE INFORMATION PLEASE CONTACT US:

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T: +44 (0)1236 433 345 | F: +44 (0)1236 433 434 | www.retronix.com | E: info@retronix.com



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Leaded Devices

The standard process below describes how a component is managed through the process, ensuring consistent exposure to solder wave (in terms of time and temperature)



The automated vacuum pickup arm transports the component from the carrier tray



The component is fluxed, each side in sequence



The device is pre-heated then temperature checked with a pyrometer.



Each side dipped under nitrogen in wave



The component is returned to the tray, or the process is repeated



Component Cleaning



Re-Baked & Packed

BGA's

The process below is completely controllable and automatic, and most importantly includes zero reflow cycles, thereby meeting the component manufacturer's specification



Existing spheres removed



Laser Reballing



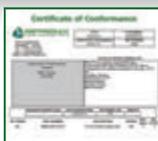
Component Cleaning



Re-Packed and Packed

Verification Tests

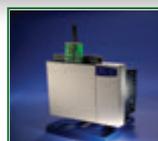
We offer a range of in house tests to verify process conformity (C of C)



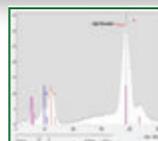
Certificate of Conformity



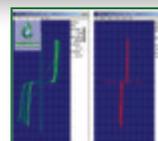
Solderability Test



Ionic Contamination Test



XRF Analysis - To Verify Alloy



Electrical Test



Mechanical Test

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